



Material Content Data Sheet



Sales Product Name		BTT6020-1EKA		Issued		1. August 2018		
MA#		MA001618496						
Package		PG-DSO-14-47		Weight*		150.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.172	2.11	2.11	21061	21061
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		459	
	non noble metal	iron	7439-89-6	1.383	0.92		9185	
wire	non noble metal	copper	7440-50-8	56.175	37.29	38.27	372933	382692
	non noble metal	copper	7440-50-8	0.713	0.47	0.47	4733	4733
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1118
encapsulation	plastics	epoxy resin	-	7.746	5.14		51425	
	inorganic material	silicondioxide	60676-86-0	76.282	50.64	55.89	506420	558963
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16409	16409
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9761	9761
glue	plastics	epoxy resin	-	0.168	0.11		1117	
	noble metal	silver	7440-22-4	0.793	0.53	0.64	5264	6381
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com